

## MOUNTING FOR A PACKAGE CONTAINING A CHIP

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### ABSTRACT OF THE DISCLOSURE

10 A mounting for a package containing a semiconductor chip is disclosed, along  
with methods of making such a mounting. The mounting includes a substrate having a  
mounting surface with conductive traces thereon, and an aperture extending through the  
substrate. The package includes a base, such as a leadframe or a laminate sheet, and  
input/output terminals. A chip is on a first side of the base and is electrically connected  
(directly or indirectly) to the input/output terminals. A cap, which may be a molded  
15 encapsulant, is provided on the first side of the base over the chip. The package is  
mounted on the substrate so that the cap is in the aperture, and a peripheral portion of the  
first side of the base is over the mounting surface so as to support the package in the  
aperture and allow the input/output terminals of the package to be juxtaposed with to the  
circuit patterns of the mounting surface. Because the cap is within the aperture, a height  
20 of the package above the mounting surface is minimized.